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(54) RESIN SOLUTION COMPOSITION FOR ELECTRONIC MATERIAL

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resin solution composition which is excellent in storage stability and capable of being cured at relatively low temperature and can give a cured product having an excellent balance among properties such as heat resistance, high-frequency characteristics, chemical resistance and stress relaxation properties.

SOLUTION: This composition is prepared by dissolving 100 pts.wt. siloxane polyimide-amic acid copolymer resin comprising an imide part prepared by the polycondensation reaction of an aromatic tetracarboxylic dianhydride with a siloxanediamine and an amic acid part prepared by the polyaddition reaction of an aromatic tetracarboxylic dianhydride with an aromatic diamine component other than the siloxanediamine and represented by the formula (wherein X is a residue of an aromatic tetracarboxylic dianhydride, Y is a residue of a siloxanediamine; Z is a residue of an aromatic diamine; (l) and (m) are each an integer; and (n) is a number of 1 or greater).

